

欧盟ROHS豁免条款概述

产品名称	欧盟ROHS豁免条款概述
公司名称	苏州瑞琪尔技术服务有限公司
价格	.00/个
规格参数	
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产品详情

小型日光灯中的汞含量不得超过5毫克/灯；(2002/95/EC)

Mercury in compact fluorescent lamps not exceeding 5mg per lamp.

2. 一般用途的直立日光灯中的汞含量不得超过：(2002/95/EC) - 卤化磷酸盐 (Halophosphate) <10毫克-正常的三磷酸盐(Triphosphate with normal lifetime) <5毫克-长效的三磷酸盐(Triphosphate with long lifetime) <8毫克
Mercury in straight fluorescent lamps for general purposes not exceeding: · Halophosphate 10mg;

· Triphosphate with normal lifetime 5mg; · Triphosphate with long lifetime 8mg.

3. 特殊用途的直式日光灯中的汞含量；(2002/95/EC) Mercury in straight fluorescent lamps for special purposes. 4

· 本附录中未特别提及的其它照明灯中的汞含量；(2002/95/EC) Mercury in other lamps not specifically mentioned in this Annex. 5. 阴极射线管 (cathode ray tubes)、电子部件 (electronic components) 和发光管 (fluorescent tubes) 的玻璃内的铅含量；(2002/95/EC) Lead in glass of cathode ray tubes, electronic components and fluorescent tubes. 6. 钢合金中的铅含量不应该超过0.35%、铝合金中铅含量不应该超过0.4%，铜合金中的铅含量不应该超过4%；(2002/95/EC) Lead as an alloying element in: · Steel containing up to 0.35% lead by weight; · Aluminium containing up to 0.4% lead by weight; · Copper alloy containing up to 4% lead by weight. 7. --高温融化型焊锡中的铅 (如：锡铅焊料合金中铅含量超过85%)；(2005/747/EC) --用于服务器 (servers)，存储器 (storage) 和存储阵列 (storage array systems) 和交换、信号产生和传输，以及电信网络管理的网络基础设施设备 (network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications) 中焊料中的铅；(2005/747/EC) --电子陶瓷产品中的铅 (如：高压电子装置)；(2005/747/EC) · Lead in high melting temperature types solders (i.e. lead-based alloys containing 85% by weight or more lead). · Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunication. · Lead in electronic ceramic parts (e.g. piezoelectric devices). 8. 电气连接的触点 (electrical contacts) 中镉及镉化合物的使用不限，以及91/338/EEC指令禁止以外的镉镀层中的镉；(2005/747/EC) Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations. 9. 在吸收式电冰箱中作为碳钢冷却系统防腐剂的六价铬。(2002/95/EC) Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators. 9a. 聚合物 (Polymeric) 中十溴二苯醚的应用。(2005/717/EC) DecaBDE in polymeric applications. 9b. 用于铅青铜轴承外壳 (lead-bronze bearing shells and bushes) 的铅；(2005/717/EC) Lead in lead-bronze bearing shells and bushes. 10. 顺应针联接系统 (compliant pin connectors systems) 中使用的铅；(2005/747/EC) Lead used in compliant pin connectors systems. 11. 热导项枪钉模组 (thermal conduction module c-

ring)涂层中所用的铅；(2005/747/EC) Lead as a coating material for the thermal conduction module c-ring. 12、光学玻璃及滤光玻璃 (optical and filter glass) 中所用的铅；(2005/747/EC) Lead and cadmium in optical and filter glass. 13、微处理器针脚及封装联接所使用的含有80-85%铅的复合 (含有超过两种组分) 焊料中的铅；(2005/747/EC) Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight. 14、倒装芯片封装中半导体芯片及载体之间形成可靠联接所用焊料中的铅；(2005/747/EC) Lead in solder to complete a viable electrical connection between a semiconductor die and carrier within an integrated circuit Flip Chip packages. 15. 直立式的钨丝灯，若其灯管含有硅酸盐涂布，则可含铅；(2006/310/EC) Lead in linear incandescent lamps with silicate coated tubes. 16. 卤化铅作为发光源，并用于探照用途的HID灯中，则可含铅；(2006/310/EC) Lead halide as a radiant agent in High Intensity Discharge (HID) lamps used for professional reprography application. 17. 若铅作为触发源而包含于荧光粉中 (铅含量1wt%或更少)，且此荧光粉是用于含有如BSP(BaSi2O5:Pb)等磷光剂的太阳灯 (suntanning lamps) 的放电灯管中，或者此荧光粉是用于含有如SMS ((Sr, Ba)2MgSi2O7:Pb) 等磷光剂的特殊灯，这些特殊灯的用途包括用于含二氮化合物的电子翻印、平板印刷、补虫灯、光化学或医疗疗程等等，则可含铅；(2006/310/EC) Lead as an activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr, Ba)2MgSi2O7:Pb). 18. 铅作为汞齐 (即汞合金) 中的特定成分，如PbBiSn - Hg或PbInSn - Hg中，且此汞齐作为主要汞齐，或如PbSn - Hg用于辅助汞齐中，且这些汞齐使用于节能灯泡 (ESL) 中，则可含铅；(2006/310/EC) Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL). 19. LCD中用于保护平面荧光灯 (flat fluorescent lamps) 的前后支撑物的玻璃中可含氧化铅。(2006/310/EC) Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD). 20. 用在硼硅酸盐玻璃表面瓷釉上的印刷油墨中的铅及镉。(2006/691/EC) Lead and cadmium in printing inks for the application of enamel on borosilicate glass. 22. 在光纤通讯系统中的稀土铁石榴石法拉第旋转器中的杂质铅。(2006/691/EC) Lead as an impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communication systems. 21. 小螺距零部件表面处理中的铅 (螺距不超过0.65mm且带镍铁边框的连接器，以及螺距不超过0.65mm且带铜边框的连接器不在豁免范围之内)。(2006/691/EC) Lead in finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with NiFe lead frames and lead finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with copper lead-frames. 22. 通孔盘状及平面阵列陶瓷多层电容器的焊料所含的铅。(2006/691/EC) Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors. 23. 等离子显示屏 (PDP) 及表面传导式电子发射显示器 (SED) 构件中所用的氧化铅，比较典型的例子：玻璃前后绝缘层中的氧化铅、总铅电极中的氧化铅、黑条 (彩色显像管) 中的氧化铅、地址电极中的氧化铅、阻挡层肋柱中的氧化铅、密封玻璃料中的氧化铅，以及封装玻璃中的氧化铅、环状玻璃中的氧化铅、油墨中的氧化铅。(2006/691/EC) Lead oxide in plasma display panels (PDP) and surface conductive electron emitter displays (SED) used in structural elements; notably in the front and rear